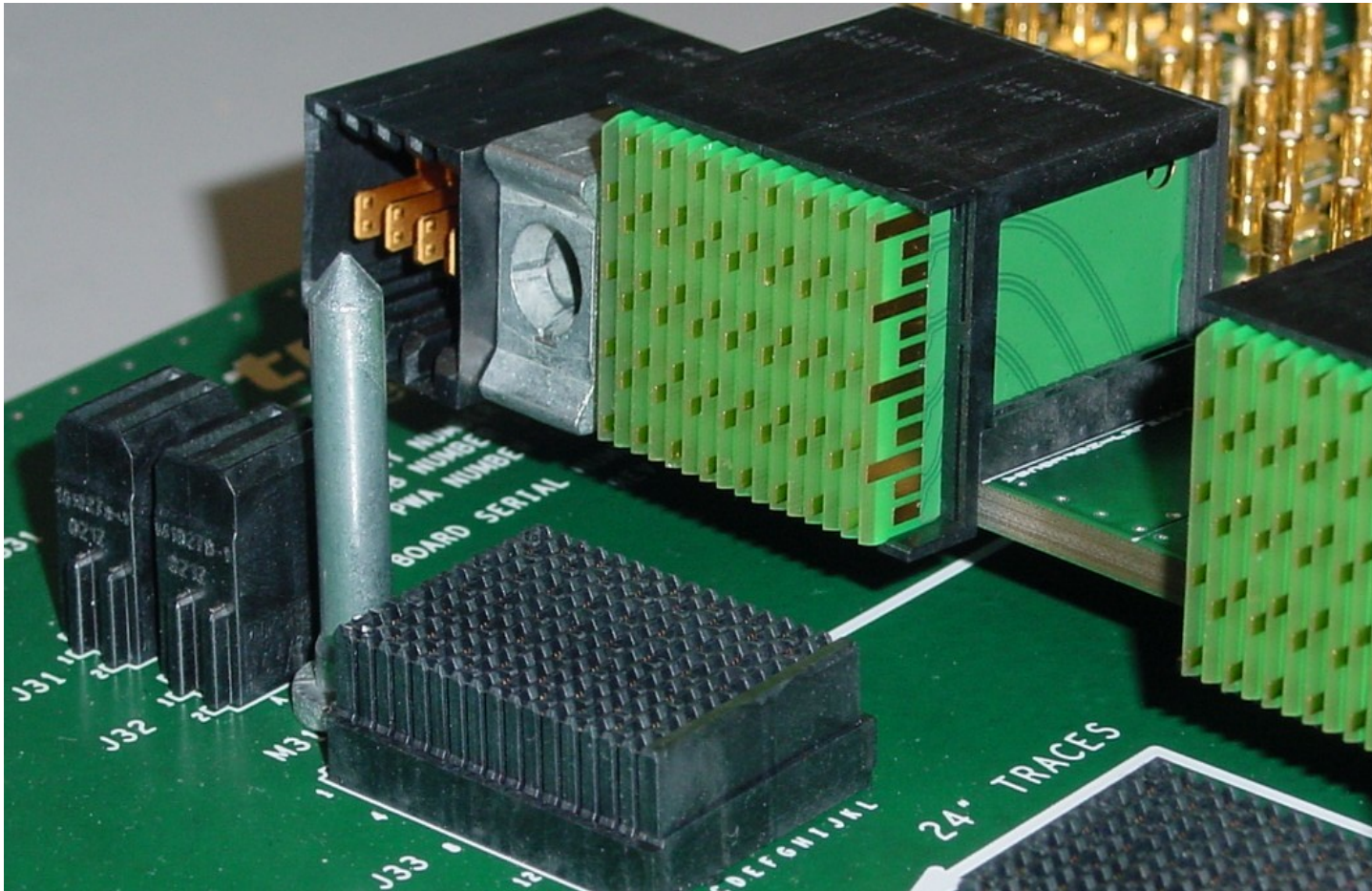
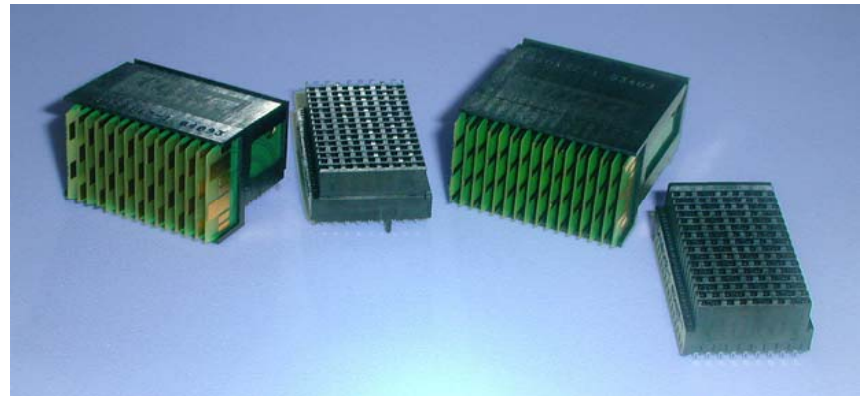


MULTIGIG RT Product

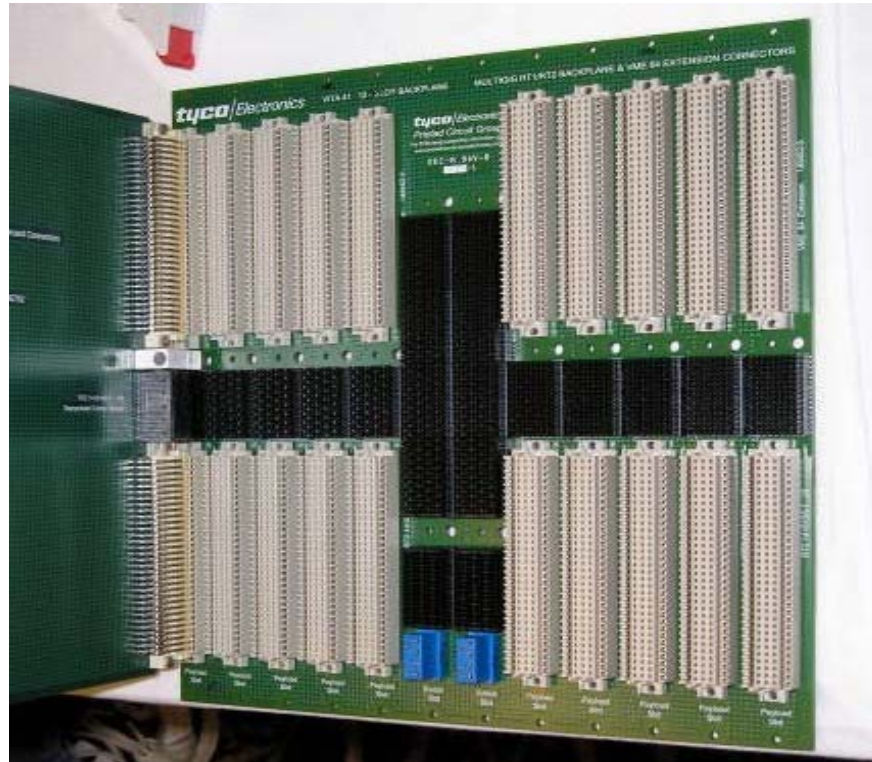


MULTIGIG RT Product - Applications

- All High Density/High Performance Backplane Applications
- Telecommunications
 - Switching Equipment
 - Transmission Equipment
 - HUBS/Routers
- Computers/ Peripherals
 - Servers
 - Networking Equipment
 - Mass Storage



MULTIGIG RT Product - Applications



Actual Vita 41, 12 slot Backplane.
Vita 41, referred to as VXS, is the next
Generation of VME Backplanes

MULTIGIG RT Product - Product Line Overview

- 3 Tiers of product
 - **Tier 1** – High Density/Lower Performance
 - **Tier 2** – High Density/High Performance
 - **Tier 3** – Lower Density/Highest Performance
- Pin-Less Backplane Connector System
- Differential Pairs, Single-ended, and Power lines within one module.
- Press-fit PCB Attach
- Power Modules for higher current, with Sacrificial Anode
- 3 levels of sequencing available on Signal Modules, and 3 levels on Power Modules.
- Guide Modules (3 types) are available

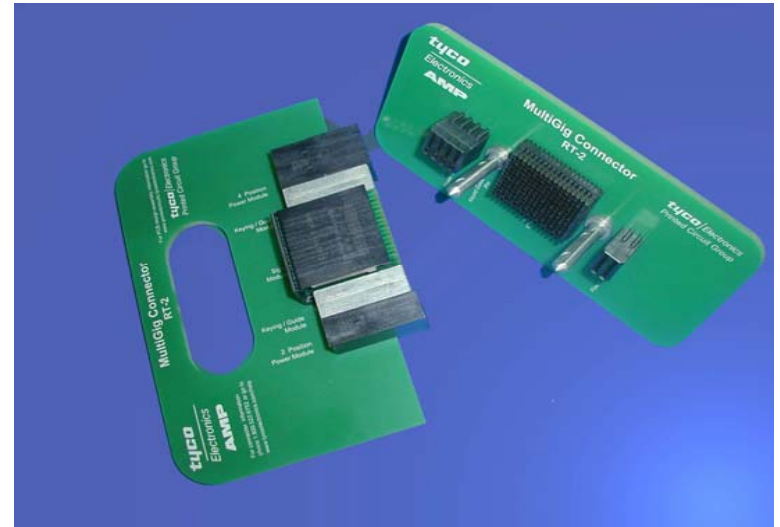
Product Line Overview Continued

Density

- Tier 1
 - 0.8" Card Pitch 113 lines/inch
 - 1.0" Card Pitch 141 lines/inch
- Tier 2
 - 0.8" Card Pitch 85 lines/inch
 - 1.0" Card Pitch 113 lines/inch
 - 1.2" Card Pitch 141 lines/inch
- Tier 3
 - 0.8" Card Pitch 63 lines/inch
 - 1.0" Card Pitch 85 lines/inch

Electrical Performance

- Tier 1 3.125 Gbps
- Tier 2 10 Gbps
- Tier 3 10+ Gbps



MULTIGIG RT Marketing Board With Signal Modules, Power Modules And Guide Modules

Product Line Overview Continued

Signal Options Available: 0.8" Shown

Differential Wafers ==>

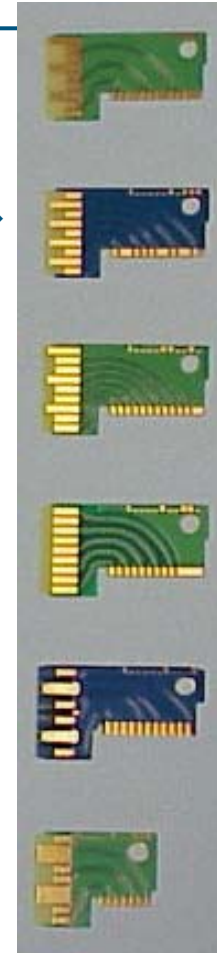
Single-Ended w/ 1:1 S/G ratio =>

Single-ended w/ 2:1 S/G ratio =>

Open Pin Field (no reference ground) =>

Mixed, Diff and S/E Lines =>

Custom, Vita 41, Mixed ==>



Each of the above wafers can be assembled into a daughter card housing to meet the customers needs.

Product Line Overview Continued

Power Options Available:

Up to 4 Power lines/wafer ==>>>

Total of 19 AMPS/wafer

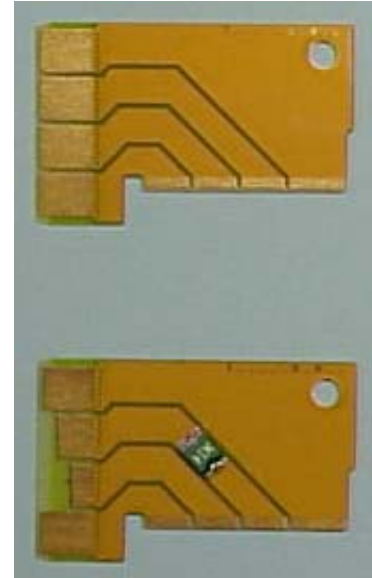
Options with integrated Polyswitch Device
for Hot-Swap Applications =>

(in Development)

Power Connectors =>

2 and 4 positions available

Power wafers can be assembled, along with the many signal options, into a daughter card housing to meet the customers needs.

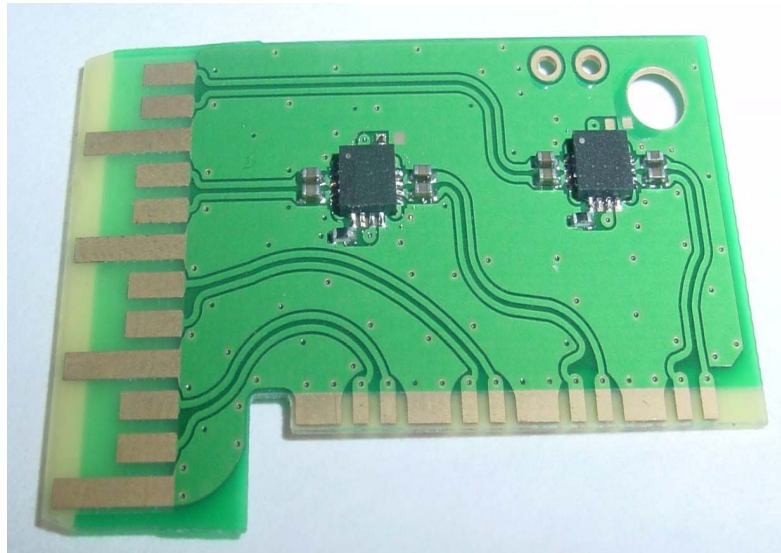


Product Line Overview Continued

Future Development Activity

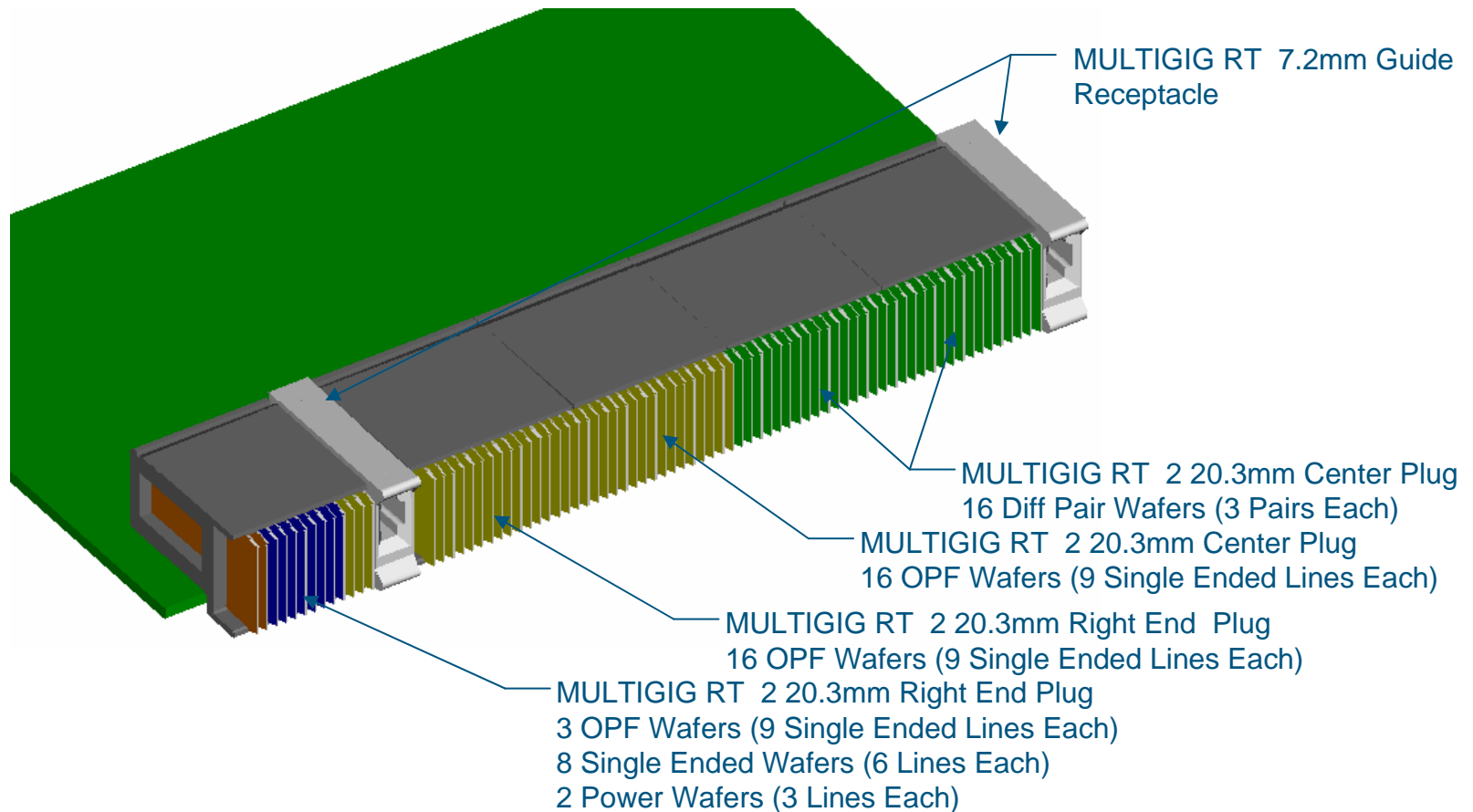
Active Wafers:

Shown below is a 10Gbps Active Equalization Chip integrated onto a PCB Wafer.



MULTIGIG RT Product

Typical MULTIGIG RT Product Implementation



MULTIGIG RT Product

Features

Pin-less Backplane

PCB construction

Bellcore Compliant

Modular Design

Skew Control

Flat-Rock Assembly

Benefits

No Pins to Bend

Customization

Proven Reliability

End to end stacking

Diff pairs are matched

No Special Tooling Req'd

MULTIGIG RT Product Specifications

- VITA 41 Specification (Next generation VME Bus called VXS)
- Bellcore Compliant
- UL & CSA approvals in process

MULTIGIG RT Product Support Materials

- Product Website: www.multigigrt.com
- Product Catalog: # 1773095
- High Speed Backplane Interconnect Solutions Brochure: #1654263-1
- Product Specification (Signal): 108-2072
- Product Specification (Power): 108-2062
- Application Specification (Signal): 114-13056
- Application Specification (Power): 114-13062
- Performance Reports (www.tycoelectronics.com/products/simulation):
 - Electrical Performance(T1): Report #21GC014
 - Footprint Optimization (T2): #R20GC009

MULTIGIG RT Product Support Materials

- 3D mechanical models (IGES and Pro/E) available through:
 - tycoCAD@tycoelectronics.com
- Electrical models (single line and multi-line) available through email address:
 - modeling@tycoelectronics.com
- or website:
 - www.tycoelectronics.com/products/simulation

Support Materials – Suggested Samples

- Tier 1 P/N's
 - 1410420-1 Daughtercard Connector (Plug)
 - 1410421-1 Backplane Connector (Receptacle)
- Tier 2 P/N's
 - 1410187-3 Daughtercard Connector (Plug)
 - 1410140-1 Backplane Connector (Receptacle)